

Vishay High Power Products

FlipKY® Chip Scale Package Schottky Barrier Rectifier

IQR



FlipKY[®]

PRODUCT SUMMARY I_{F(AV)} 1.5 A V_R 40 V

FEATURES

- Ultra low V_F per footprint area
- · Low leakage
- · Low thermal resistance
- · One-fifth footprint of SMA
- Super low profile (0.6 mm)
- · Available tested on tape and reel

APPLICATIONS

- · Reverse polarity protection
- · Current steering
- · Freewheeling
- Flyback
- Oring

DESCRIPTION

Vishay's FlipKY® product family utilizes wafer level chip scale packaging to deliver Schottky diodes with the lowest V_F to PCB footprint area in industry. The four bump 1.5 x 1.5 mm devices can deliver up to 1.5 A and occupy only 2.3 mm² of board space. The anode and cathode connections are made through solder bump pads on one side of the silicon enabling designers to strategically place the diodes on the PCB. This design not only minimizes board space but also reduces thermal resistance and inductance, which can improve overall circuit efficiency.

Typical applications include hand-held, portable equipment such as cell phones, MP3 players, bluetooth, GPS, PDAs, and portable hard disk drives where space savings and performance are crucial.

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL	CHARACTERISTICS	MAX.	UNITS			
V _{RRM}		40	V			
I _{F(AV)}	Rectangular waveform	1.5	۸			
I _{FSM}		250	A			
V _F	at 1.5 Apk, T _J = 125 °C	0.42	V			
T _J		- 55 to 150	°C			

VOLTAGE RATINGS					
PARAMETER	SYMBOL	FCSP240LTR	UNITS		
Maximum DC reverse voltage	V _R	40	V		
Maximum working peak reverse voltage	V_{RWM}	40	V		

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FCSP240LTR

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ABSOLUTE MAXIMUM RATINGS						
PARAMETER	ARAMETER SYMBOL TEST CONDITIONS		TIONS	VALUES	UNITS	
Maximum average forward current	I _{F(AV)}	50 % duty cycle at T _{PCB} = 97 °C	C, rectangular waveform	1.5		
Maximum peak one cycle	I _{FSM}	5 μs sine or 3 μs rect. pulse	Following any rated load condition and with rated	250	Α	
non-repetitive surge current at 25 °C		10 ms sine or 6 ms rect. pulse	V _{RRM} applied	21		
Non-repetitive avalanche energy	E _{AS}	$T_J = 25$ °C, $I_{AS} = 2.0$ A, $L = 5.0$ mH		10	mJ	
Repetitive avalanche current	I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical		2.0	Α	

ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		TYP.	MAX.	UNITS
	V _{FM} ⁽¹⁾	at 1.5 A	T _J = 25 °C	0.45	0.49	V
Maximum forward		at 3 A		0.55	0.60	
voltage drop See fig. 1		at 1.5 A	T _J = 125 °C	0.37	0.42	
5		at 3 A		0.51	0.57	
	I _{RM} ⁽¹⁾	T _J = 25 °C	V _R = Rated V _R	15	80	μA mA
			V _R = 20 V	3.5	20	
			V _R = 10 V	2	10	
Maximum reverse			V _R = 5 V	1.5	5	
leakage current See fig. 2		T _J = 125 °C	V _R = Rated V _R	9	20	
			V _R = 20 V	3.5	8	
			V _R = 10 V	2.5	6	
			V _R = 5 V	2	5	
Maximum junction capacitance	Ст	$V_R = 5 V_{DC}$ (test signal range 100 kHz to 1 MHz) 25 °C		-	160	pF
Maximum voltage rate of charge	dv/dt	Rated V _R		=	10 000	V/µs

 $^{^{(1)}\,}$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum junction temperature range	T _J ⁽¹⁾		- 55 to 150	°C		
Maximum storage temperature range	T _{Stg}		- 55 10 150			
Typical thermal resistance, junction to PCB	R _{thJL} (2)	DC operation	40	°C/W		
Maximum thermal resistance, junction to ambient	R_{thJA}		62	C/VV		

Notes

 $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}} \quad \text{thermal runaway condition for a diode on its own heatsink}$

(2) Mounted 1" square PCB



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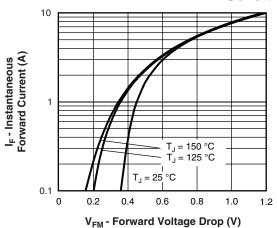


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

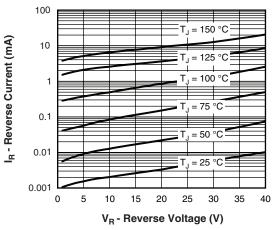


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

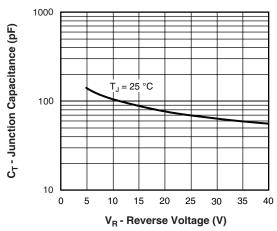
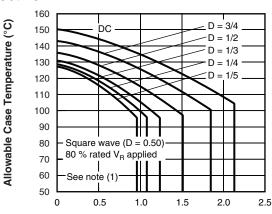


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)



I_{F(AV)} - Average Forward Current (A)
Fig. 4 - Maximum Allowable Case Temperature vs.
Average Forward Current (Per Leg)

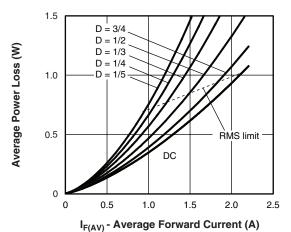


Fig. 5 - Forward Power Loss Characteristics (Per Leg)

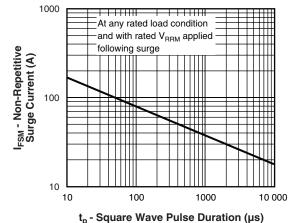


Fig. 6 - Maximum Non-Repetitive Surge Current (Per Leg)

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{th,JC}$; $Pd = Forward power loss = I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); $Pd_{REV} = Inverse$ power loss = $V_{R1} \times I_{R}$ (1 - D); I_{R} at 80 % V_{R} applied

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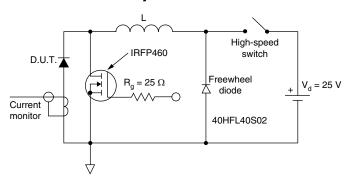
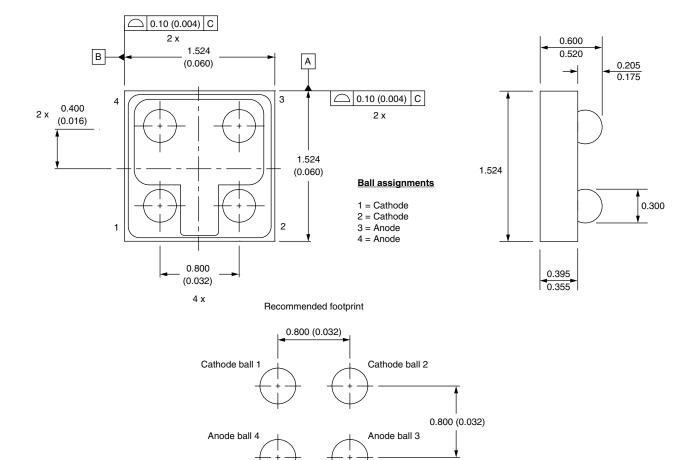


Fig. 7 - Unclamped Inductive Test Circuit

DIMENSIONS in millimeters (inches)



Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- · Controlling dimension: millimeter

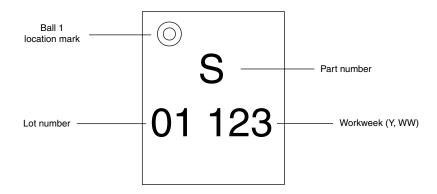
4 x Ø 0.35 (0.014)



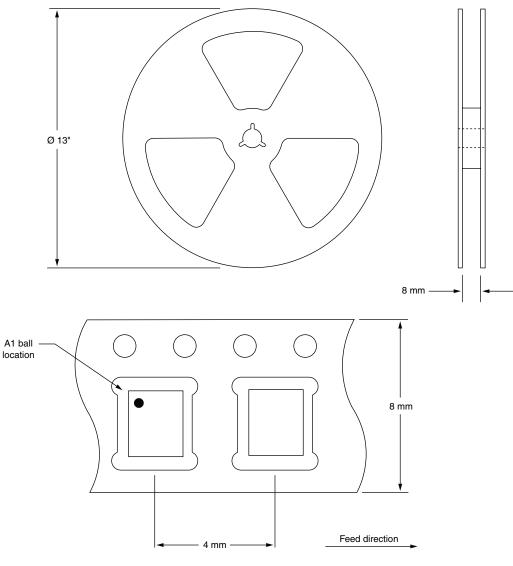
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PART MARKING INFORMATION



TAPE AND REEL INFORMATION



Conforms to EIA-481 and EIA-541



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